

## Description

The AP2302BI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a

Battery protection or in other Switching application.

### **General Features**

 $V_{DS} = 20V I_{D} = 2.3A$ 

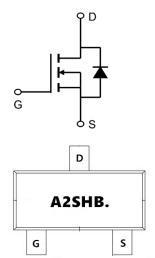
 $R_{DS(ON)}$  < 56m $\Omega$ @  $V_{GS}$ =4.5V



Battery protection

Load switch

Uninterruptible power supply





## **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
AP2302BI	SOT-23	A2SHB.	3000

Absolute Maximum Ratings (T<sub>C</sub>=25<sup>°</sup>C unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	Drain-source Voltage 20		V
V <sub>G</sub> s	Gate-source Voltage ±12		V
I <sub>D@</sub> T <sub>A</sub> =25℃	Continuous Drain Current VGS @ 4.5V 2.3		Α
I <sub>D@</sub> T <sub>A</sub> =70℃	Continuous Drain Current VGS @ 4.5V 1.8		А
IDM	Pulsed Drain Current <sup>A</sup>	14	А
P <sub>D</sub>	Total Power Dissipation @ T <sub>A</sub> =25℃ 0.7		W
R₀JA	Thermal Resistance Junction-to-Ambient@Steady State 178		°C/W
TJ ,TSTG	TSTG Junction and Storage Temperature Range -55~+150		$^{\circ}$ C





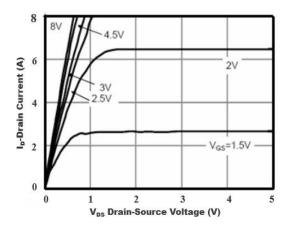
## Electrical Characteristics (T $_{J}$ =25 $^{\circ}$ C, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	20	21		V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V,V <sub>GS</sub> =0V,T <sub>C</sub> =25°C			1	μΑ
IGSS	Gate-Body Leakage Current	V <sub>GS</sub> = ±12V, V <sub>DS</sub> =0V			±100	nA
VGS(th)	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	0.52	0.66	0.9	V
RDS(ON)	Static Drain-Source On-	V <sub>GS</sub> = 4.5V, I <sub>D</sub> =2.0A		43	56	mΩ
KD3(ON)	Resistance	V <sub>GS</sub> = 2.5V, I <sub>D</sub> =1.5A		58	78	11122
C <sub>iss</sub>	Input Capacitance			280		
Coss	Output Capacitance	V <sub>DS</sub> =10V,V <sub>GS</sub> =0V,f=1MHZ		46		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			29		
Qg	Total Gate Charge			2.9		
Q <sub>gs</sub>	Gate Source Charge	V <sub>GS</sub> =4.5V,V <sub>DS</sub> =10V,I <sub>D</sub> =3.0A		0.4		nC
$Q_{\mathrm{gd}}$	Gate Drain Charge			0.6		
tD(on)	Turn-on Delay Time			13		
tr	Turn-on Rise Time	$V_{GS}$ =4.5V, $V_{DD}$ =10V, R <sub>L</sub> =1.5 $\Omega$ , R <sub>GEN</sub> =3 $\Omega$		54		ns
tD(off)	Turn-off Delay Time			18		
t <sub>f</sub>	Turn-off Fall Time			11		
Is	Maximum Body-Diode Continuous Current				3.0	Α
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =3.0A,V <sub>GS</sub> =0V			1.2	V

#### Note:

- 1. Pulse Test: Pulse Width $\leq$ 300us,Duty cycle  $\leq$ 2%.
- $2_{\times}$  Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.





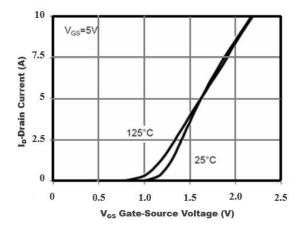


Figure 1. Output Characteristics

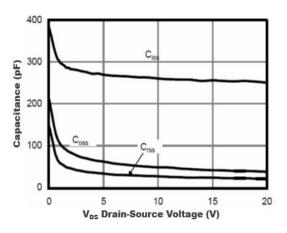


Figure 2. Transfer Characteristics

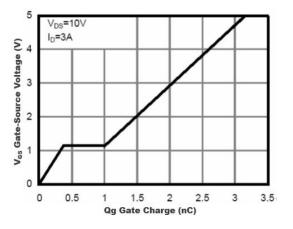


Figure 3. Capacitance Characteristics

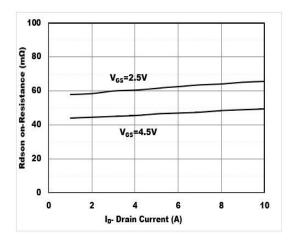


Figure4. Gate Charge

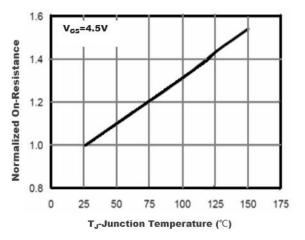
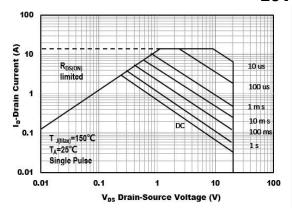


Figure 5. Drain-Source on Resistance

Figure6. Drain-Source on Resistance









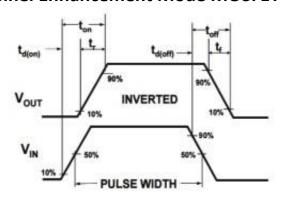


Figure8. Switching wave



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Edition	Date	Change
Rve3.8	2018/1/31	Initial release
Rve3.9	2019/12/01	Reduce RDS(on)

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